

SSM3K16CT

High-Speed Switching Applications

Analog Switch Applications

- Suitable for high-density mounting due to compact package
- Low ON-resistance : $R_{on} = 3.0 \Omega$ (max) (@ $V_{GS} = 4 V$)
: $R_{on} = 4.0 \Omega$ (max) (@ $V_{GS} = 2.5 V$)
: $R_{on} = 15 \Omega$ (max) (@ $V_{GS} = 1.5 V$)

Absolute Maximum Ratings (Ta = 25°C)

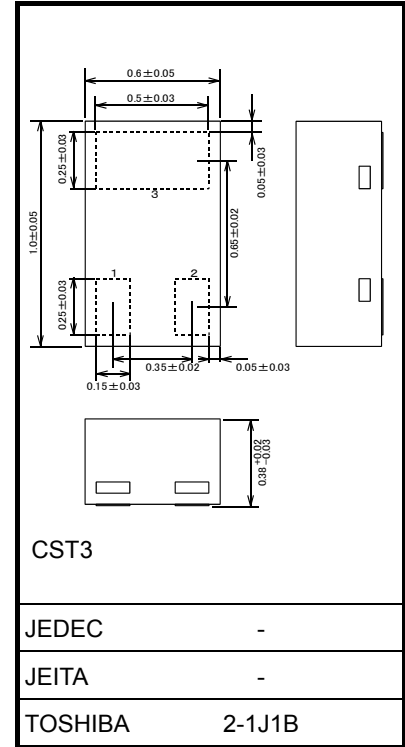
| Characteristics | | Symbol | Rating | Unit |
|-------------------------------------|-------|----------------|----------|------|
| Drain-Source voltage | | V_{DS} | 20 | V |
| Gate-Source voltage | | V_{GS} | ± 10 | V |
| Drain current | DC | I_D | 100 | mA |
| | Pulse | I_{DP} | 200 | |
| Drain power dissipation (Ta = 25°C) | | P_D (Note 1) | 100 | mW |
| Channel temperature | | T_{ch} | 150 | °C |
| Storage temperature | | T_{stg} | -55~150 | °C |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

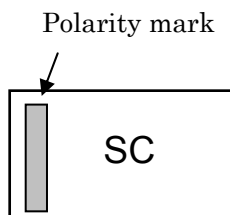
Note 1: Mounted on FR4 board
(10 mm × 10 mm × 1.0 t, Cu Pad: 100 mm²)

Unit: mm



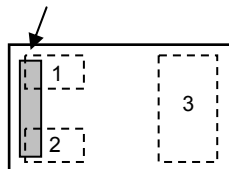
Weight: 0.75 mg (typ.)

Marking (Top View)



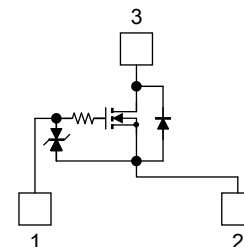
Pin Condition (Top View)

Polarity mark (on the top)



1. Gate
 2. Source
 3. Drain
- *Electrodes: on the bottom

Equivalent Circuit



Handling Precaution

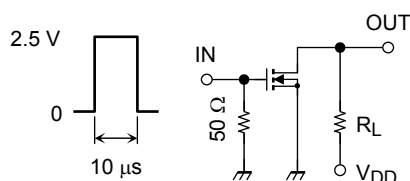
When handling individual devices that are not yet mounted on a circuit board, ensure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

Electrical Characteristics (Ta = 25°C)

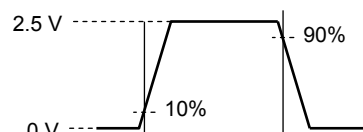
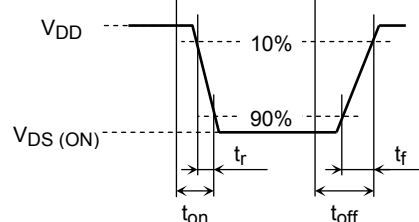
| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|--------------------------------|---------------|--|-----|------|---------|---------------|
| Gate leakage current | I_{GSS} | $V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$ | — | — | ± 1 | μA |
| Drain-Source breakdown voltage | $V_{(BR)DSS}$ | $I_D = 0.1 \text{ mA}, V_{GS} = 0$ | 20 | — | — | V |
| Drain cut-off current | I_{DSS} | $V_{DS} = 20 \text{ V}, V_{GS} = 0$ | — | — | 1 | μA |
| Gate threshold voltage | V_{th} | $V_{DS} = 3 \text{ V}, I_D = 0.1 \text{ mA}$ | 0.6 | — | 1.1 | V |
| Forward transfer admittance | $ Y_{fs} $ | $V_{DS} = 3 \text{ V}, I_D = 10 \text{ mA}$ | 40 | — | — | mS |
| Drain-Source ON-resistance | $R_{DS(ON)}$ | $I_D = 10 \text{ mA}, V_{GS} = 4 \text{ V}$ | — | 1.5 | 3.0 | Ω |
| | | $I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$ | — | 2.2 | 4.0 | |
| | | $I_D = 1 \text{ mA}, V_{GS} = 1.5 \text{ V}$ | — | 5.2 | 15 | |
| Input capacitance | C_{iss} | $V_{DS} = 3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$ | — | 9.3 | — | pF |
| Reverse transfer capacitance | C_{rss} | $V_{DS} = 3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$ | — | 4.5 | — | pF |
| Output capacitance | C_{oss} | $V_{DS} = 3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$ | — | 9.8 | — | pF |
| Switching time | Turn-on time | $V_{DD} = 3 \text{ V}, I_D = 10 \text{ mA}, V_{GS} = 0 \sim 2.5 \text{ V}$ | — | 70 | — | ns |
| | Turn-off time | | — | 125 | — | |

Switching Time Test Circuit

(a) Test circuit



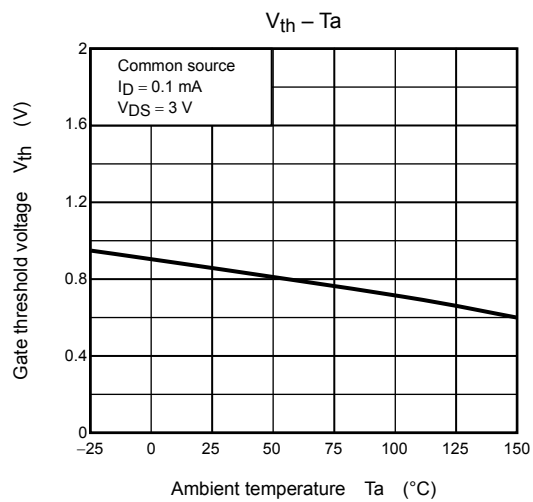
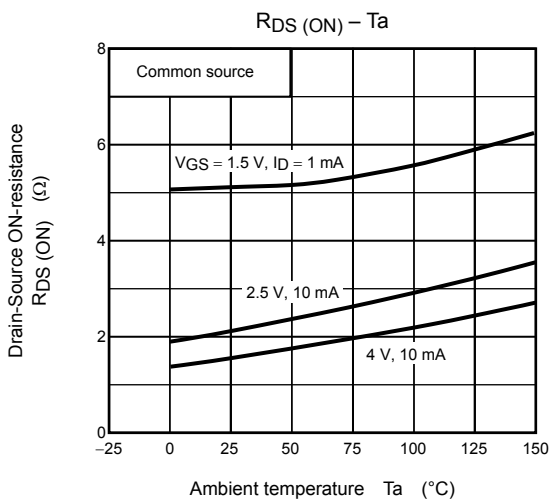
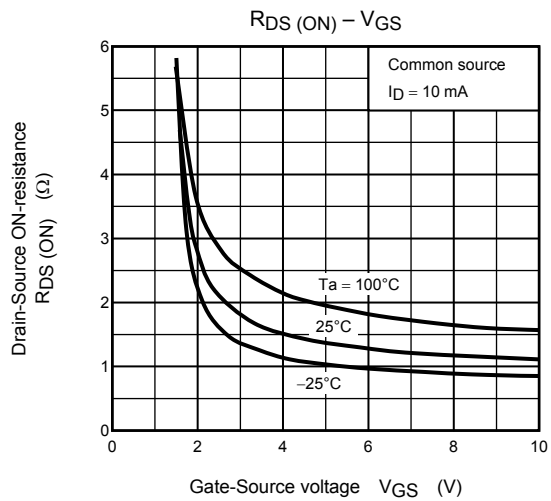
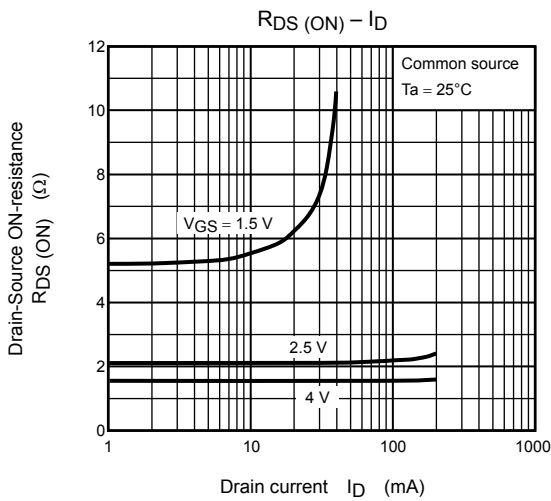
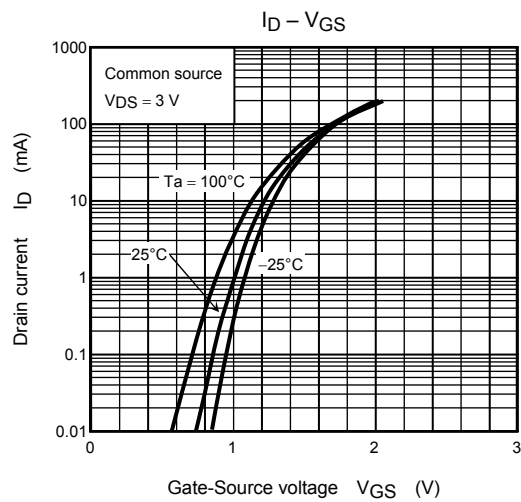
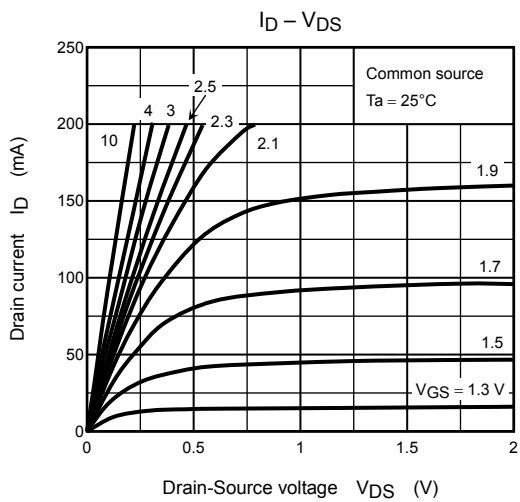
$V_{DD} = 3 \text{ V}$
 Duty $\leq 1\%$
 V_{IN} : $t_r, t_f < 5 \text{ ns}$
 $(Z_{out} = 50 \Omega)$
 Common Source
 $T_a = 25^\circ\text{C}$

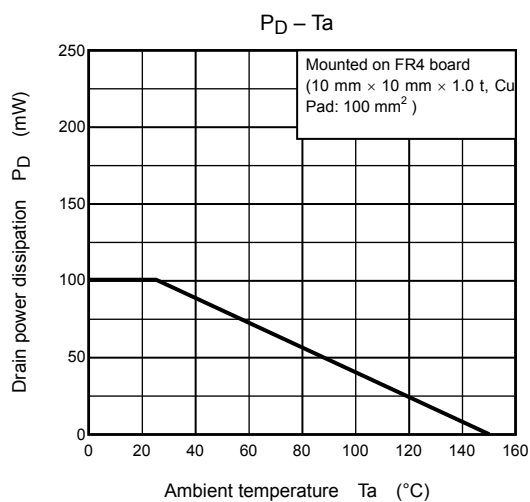
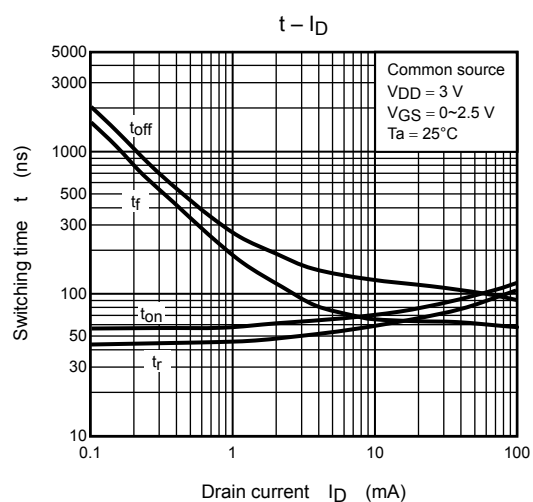
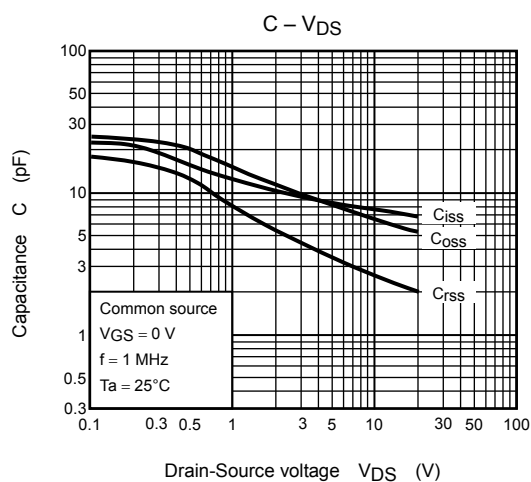
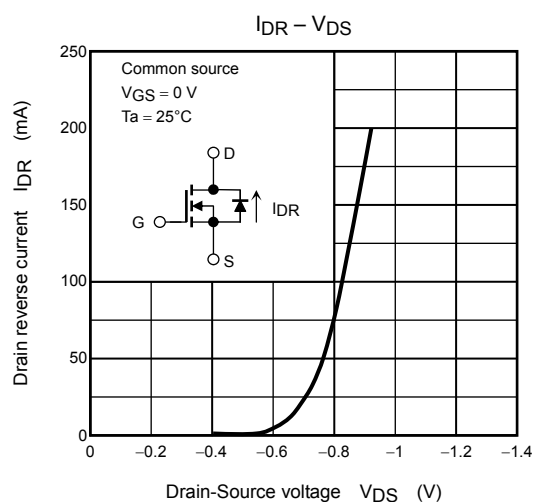
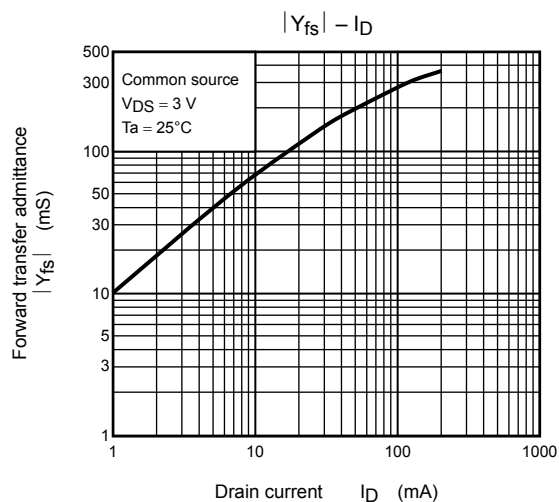
(b) V_{IN} (c) V_{OUT} 

Precaution

V_{th} can be expressed as the voltage between gate and source when the low operating current value is $I_D = 100 \mu\text{A}$ for this product. For normal switching operation, $V_{GS(on)}$ requires a higher voltage than V_{th} and $V_{GS(off)}$ requires a lower voltage than V_{th} . (The relationship can be established as follows: $V_{GS(off)} < V_{th} < V_{GS(on)}$.)

Take this into consideration when using the device.





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20070701-EN GENERAL

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